

IN THE CLAIMS

Please amend the claims as follows. This listing of claims replaces all prior versions and listings of claims in the application:

1. (Currently Amended) A method for the monitoring of a manufacturing process of a plurality of physical objects, the method comprising the steps of:

performing an analysis by using values of at least one process parameter of the manufacturing process of the plurality of physical objects ~~object~~;

determining that at least one physical object of the plurality of physical objects does determines when they do not satisfy a prescribed selection criterion; and

marking the at least one physical object ~~objects~~ in such a way that the at least one marked physical object must associated physical objects are to be sent for a special measurement; and

removing the at least one marked physical object from the manufacturing process.

2. (Currently Amended) The method of as claimed in claim 1 wherein, ~~in which~~ the physical object is a wafer.

3. (Currently Amended) The method of claim 1 wherein as claimed in claim 1 or 2, ~~in which~~ the analysis is a statistical analysis.

4. (Currently Amended) The method of claim 1 wherein as claimed in one of claims 1 to 3, ~~in which~~ the values of the at least one process parameter are measured when the plurality of physical objects ~~physical object~~ is being manufactured.

5. (Currently Amended) The method of claim 1, further comprising: as claimed in one of claims 1 to 4, ~~in which~~

sending the at least one marked physical object is sent for a special measurement.